

FDI Device Package Certificate of Registration



<u>TOKYO KEISO</u> Manufacturer	<u>AM/H</u> Model Name
<u>0082</u> Manufacturer ID (Hex)	<u>8265</u> Device Type (Hex)
<u>0203.fma</u> Device Description File Name	<u>05a67515-c69e-474f-b3a6-221585ccef2a</u> FDI Device Package ID
<u>TOKYO_KEISO.AM_H. 02.03.00.HART.fdx</u> FDI Device Package File Name	<u>02.03.00</u> FDI Package Version
<u>1.3.0</u> FDI Technology Version	<u>L2-06-1000-1040</u> Registration Number
<u>DPCTT 1.5.1</u> Test System Versions	<u>FieldComm Group Incorporated</u> Registration Authority
<u>No</u> Style Guide Implemented	<u><i>T. J. Masters</i></u> Approval
<u>2023-03-01</u> Registration Issue Date	

This document is to certify that the above FDI Package is in conformity with FCG.PD10026 and FCG.PD10028 and meets the requirements to be "REGISTERED".



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